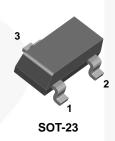
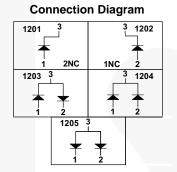


July 2015

# MMBD1201 / MMBD1202 / MMBD1203 / MMBD1204 / MMBD1205 Small Signal Diodes





## **Ordering Information**

Part Number	Top Mark	Package	Packing Method
MMBD1201	24	SOT-23 3L	Tape and Reel
MMBD1202	25	SOT-23 3L	Tape and Reel
MMBD1203	26	SOT-23 3L	Tape and Reel
MMBD1204	27	SOT-23 3L	Tape and Reel
MMBD1205	28	SOT-23 3L	Tape and Reel

## Absolute Maximum Ratings(1), (2)

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only. Values are at  $T_A = 25^{\circ}\text{C}$  unless otherwise noted.

Symbol	Parameter		Value	Unit
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage		100	V
I <sub>F(AV)</sub>	Average Rectified Forward Current		200	mA
I <sub>FSM</sub>	Non-Repetitive Peak Forward Surge Current	Pulse Width = 1.0 second	1.0	Α
		Pulse Width = 1.0 microsecond	2.0	
T <sub>STG</sub>	Storage Temperature Range		-55 to +150	°C
TJ	Operating Junction Temperature		150	°C

### Notes

- 1. These ratings are based on a maximum junction temperature of 150°C.
- These are steady-state limits. Fairchild Semiconductor should be consulted on applications involving pulsed or low-duty-cycle operations.

# **Thermal Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Value	Unit
P <sub>D</sub>	Power Dissipation	350	mW
	Derate Above 25°C	2.8	mW/°C
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	357	°C/W

## **Electrical Characteristics**

Values are at  $T_A = 25$ °C unless otherwise noted.

Symbol	Parameter	Conditions	Min.	Max.	Unit
V <sub>R</sub>	Breakdown Voltage	I <sub>R</sub> = 100 μA	100		V
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 1.0 mA	550	600	mV
		I <sub>F</sub> = 10 mA	660	740	mV
		I <sub>F</sub> = 100 mA	820	920	mV
		I <sub>F</sub> = 200 mA	0.87	1.0	V
		I <sub>F</sub> = 300 mA		1.1	V
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 20 V		25	nA
		V <sub>R</sub> = 50 V	1	50	nA
		V <sub>R</sub> = 50 V, T <sub>A</sub> = 150°C		100	μΑ
C <sub>T</sub>	Total Capacitance	V <sub>R</sub> = 0, f = 1.0 MHz		2.0	pF
t <sub>rr</sub>	Reverse Recovery Time	$I_F = I_R = 10 \text{ mA}, I_{RR} = 1.0 \text{ mA},$ $R_L = 100 \Omega$		4.0	nS

## **Typical Performance Characteristics**

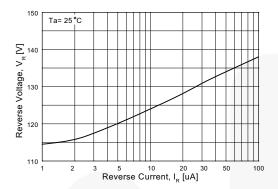


Figure 1. Reverse Voltage vs. Reverse Current BV @ I\_R = 1.0 to 100  $\mu$ A

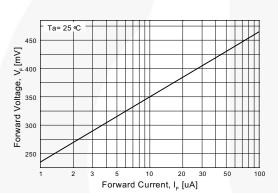


Figure 3. Forward Voltage vs. Forward Current V<sub>F</sub> @ I<sub>F</sub> = 1.0 to 100  $\mu$ A

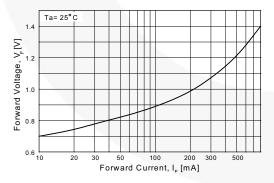


Figure 5. Forward Voltage vs. Forward Current  $V_F @ I_F = 10 \text{ to } 800 \text{ mA}$ 

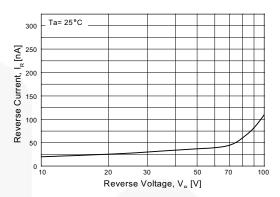


Figure 2. Reverse Current vs. Reverse Voltage  $I_R @ V_R = 10 \text{ to } 100 \text{ V}$ 

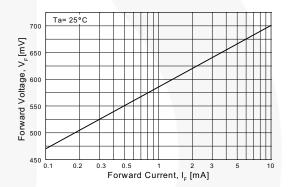


Figure 4. Forward Voltage vs. Forward Current  $V_F @ I_F = 0.1$  to 10 mA

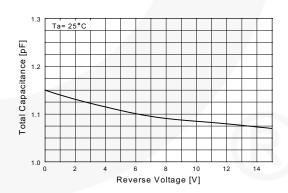


Figure 6. Total Capacitance vs. Reverse Voltage

# **Typical Performance Characteristics** (Continued)

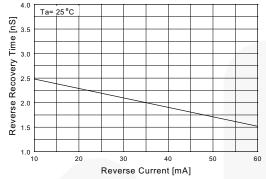


Figure 7. Reverse Recovery Time vs. Reverse Current

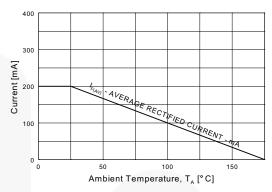


Figure 8. Average Rectified Current  $(I_{F(AV)})$  vs. Ambient Temperature  $(T_A)$ 

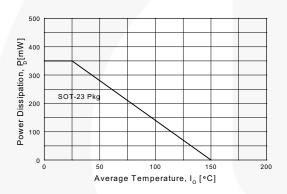


Figure 9. Power Derating Curve

## **Physical Dimensions** 0.95 2.92±0.20 3 1.40 1.30<sup>+0.20</sup><sub>-0.15</sub> 2.20 0.60 0.37 (0.29) -0.95 ⊕ 0.20M A B 1.00 1.90 1.90 LAND PATTERN RECOMMENDATION SEE DETAIL A 1.20 MAX 0.10 (0.93) □ 0.10 M C С 2.40±0.30 NOTES: UNLESS OTHERWISE SPECIFIED **GAGE PLANE** A) REFERENCE JEDEC REGISTRATION TO-236, VARIATION AB, ISSUE H. B) ALL DIMENSIONS ARE IN MILLIMETERS. 0.23 0.08 C) DIMENSIONS ARE INCLUSIVE OF BURRS, 0.25 MOLD FLASH AND TIE BAR EXTRUSIONS. D) DIMENSIONING AND TOLERANCING PER ASME Y14.5M - 1994. 0.20 MIN SEATING E) DRAWING FILE NAME: MA03DREV10 **PLANE** (0.55)**DETAIL A** SCALE: 2X

Figure 10. 3-LEAD, SOT23, JEDEC TO-236, LOW PROFILE





#### TRADEMARKS

The following includes registered and unregistered trademarks and service marks, owned by Fairchild Semiconductor and/or its global subsidiaries, and is not intended to be an exhaustive list of all such trademarks.

BitSiC™ Green FPS™

Build it Now™ Green FPS™ e-Series™

CorePLUSTM  $Gmax^{TM}$ CorePOWERTM  $GTO^{TM}$   $CROSSVOLT^{TM}$  IntelliMAXTM
CTLTM ISOPI ANARTM

Current Transfer Logic™ Making Small Speakers Sound Louder DEUXPEED® and Better™

Dual Cool™

EcoSPARK®

EfficientMax™

ESBC™

MicroPak™

MicroPak™

MicroPak™

MicroPak™

MillerDrive™ Fairchild® MotionMax™ Fairchild Semiconductor® MotionGrid® FACT Quiet Series™ MTi<sup>®</sup> FACT® FAST® MTx® MVN® FastvCore™ mWSaver® FETBench™ OptoHiT™ **FPSTM** OPTOLOGIC® OPTOPLANAR®

Power Supply WebDesigner™

PowerTrench<sup>©</sup> PowerXS™

Programmable Active Droop™

QFĔT<sup>®</sup>
QS™
Quiet Series™
RapidConfigure™

Saving our world, 1mW/W/kW at a time™

SignalWise™ SmartMax™ SMART START™

Solutions for Your Success™

SPM®
STEALTH™
SuperFET®
SuperSOT™-3
SuperSOT™-8
SupreMOS®
SyncFET™
Sync-Lock™

SYSTEM SYSTEM

TinyBoost®
TinyBuck®
TinyCalc™
TinyLogic®
TINYOPTO™
TinyPower™
TinyPWM™
TinyWire™
TranSiC™
TriFault Detect™
TRUECURRENT®

µSerDes™
SerDes™
UHC<sup>®</sup>
Ultra FRFET™
UniFET™
VCX™
VisualMax™

VCX™ VisualMax™ VoltagePlus™ XS™ Xsens™ 仙童™

#### ISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION, OR DESIGN. TO OBTAIN THE LATEST, MOST UP-TO-DATE DATASHEET AND PRODUCT INFORMATION, VISIT OUR WEBSITE AT <a href="http://www.fairchildsemi.com">http://www.fairchildsemi.com</a>. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS. THESE SPECIFICATIONS DO NOT EXPAND THE TERMS OF FAIRCHILD'S WORLDWIDE TERMS AND CONDITIONS, SPECIFICALLY THE WARRANTY THEREIN, WHICH COVERS THESE PRODUCTS.

### **AUTHORIZED USE**

Unless otherwise specified in this data sheet, this product is a standard commercial product and is not intended for use in applications that require extraordinary levels of quality and reliability. This product may not be used in the following applications, unless specifically approved in writing by a Fairchild officer: (1) automotive or other transportation, (2) military/aerospace, (3) any safety critical application – including life critical medical equipment – where the failure of the Fairchild product reasonably would be expected to result in personal injury, death or property damage. Customer's use of this product is subject to agreement of this Authorized Use policy. In the event of an unauthorized use of Fairchild's product, Fairchild accepts no liability in the event of product failure. In other respects, this product shall be subject to Fairchild's Worldwide Terms and Conditions of Sale, unless a separate agreement has been signed by both Parties.

## ANTI-COUNTERFEITING POLICY

Fairchild Semiconductor Corporation's Anti-Counterfeiting Policy. Fairchild's Anti-Counterfeiting Policy is also stated on our external website, www.fairchildsemi.com, under Terms of Use

Counterfeiting of semiconductor parts is a growing problem in the industry. All manufacturers of semiconductor products are experiencing counterfeiting of their parts. Customers who inadvertently purchase counterfeit parts experience many problems such as loss of brand reputation, substandard performance, failed applications, and increased cost of production and manufacturing delays. Fairchild is taking strong measures to protect ourselves and our customers from the proliferation of counterfeit parts. Fairchild strongly encourages customers to purchase Fairchild parts either directly from Fairchild or from Authorized Fairchild Distributors who are listed by country on our web page cited above. Products customers buy either from Fairchild directly or from Authorized Fairchild Distributors are genuine parts, have full traceability, meet Fairchild's quality standards for handling and storage and provide access to Fairchild's full range of up-to-date technical and product information. Fairchild and our Authorized Distributors will stand behind all warranties and will appropriately address any warranty issues that may arise. Fairchild will not provide any warranty coverage or other assistance for parts bought from Unauthorized Sources. Fairchild is committed to combat this global problem and encourage our customers to do their part in stopping this practice by buying direct or from authorized distributors.

### PRODUCT STATUS DEFINITIONS

**Definition of Terms** 

Definition of Terms			
Datasheet Identification	Product Status	Definition	
Advance Information	Formative / In Design	Datasheet contains the design specifications for product development. Specifications may change in any manner without notice.	
Preliminary	First Production	Datasheet contains preliminary data; supplementary data will be published at a later date. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve design.	
No Identification Needed	Full Production	Datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice to improve the design.	
Obsolete	Not In Production	Datasheet contains specifications on a product that is discontinued by Fairchild Semiconductor. The datasheet is for reference information only.	

Rev. 175

<sup>\*</sup> Trademarks of System General Corporation, used under license by Fairchild Semiconductor.